



Material Content Data Sheet



Sales Product Name		TLE75008-ESD		Issued		4. March 2019		
MA#		MA001681940						
Package		PG-TSDSO-24-21		Weight*		111.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.881	1.68	1.68	16834	16834
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142	
	non noble metal	zinc	7440-66-6	0.063	0.06		566	
	non noble metal	iron	7439-89-6	1.266	1.13		11327	
	non noble metal	copper	7440-50-8	51.392	46.00	47.20	459935	471970
wire	non noble metal	copper	7440-50-8	0.864	0.77	0.77	7729	7729
encapsulation	organic material	carbon black	1333-86-4	0.154	0.14		1378	
	plastics	epoxy resin	-	6.006	5.38		53755	
	inorganic material	silicondioxide	60676-86-0	45.176	40.43	45.95	404311	459444
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25239	25239
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11446	11446
glue	plastics	epoxy resin	-	0.143	0.13		1284	
	noble metal	silver	7440-22-4	0.676	0.61	0.74	6054	7338
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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